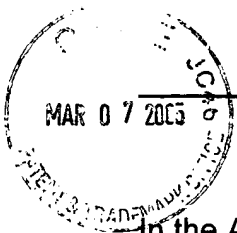


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
(Case No. 207.008-US)

In the Application of: **Lutz et al.**

Serial No: **10/627,237**

Filed: **July 25, 2003**

Title: **Anchors for Microelectromechanical Systems
Having an SOI Substrate, and Method for
Fabricating Same**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

) Group Art Unit: **2822**
)
) Examiner: **Prenty, Mark V.**
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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on March 3, 2005

Date
Michiko Sites
(person signing this certificate)
Michiko Sites
Signature

SIXTH INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Submitted herewith are two (2) sheets of a modified Form PTO-1449. Electronic copies of the U.S. patents and published U.S. patent applications identified on the attached Form PTO-1449 are found on the attached compact disc ("CD"). A paper copy of each foreign document and publication cited on the attached Form PTO-1449 is also submitted.

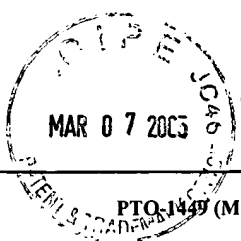
Notably, U.S. Published Patent Application 2004-0065932 is the U.S. counterpart of International Application No. WO 01/46066, both of which are identified in the attached Form PTO-1449. That published application was cited in U.S. Patent Application Serial No. 10/455,555, entitled "Microelectromechanical Systems having Trench Isolated Contacts, and Methods for Fabricating Same".

It is respectfully requested that the Examiner make his/her consideration of these documents formally of record with the next Office Action.

Respectfully submitted,

Date: March 3, 2005

Neil A. Steinberg, Reg. No. 34,735
Telephone No. 650-968-8079



PTO-1449 (Modified) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO. 207.008-US	SERIAL NUMBER 10/627,237
	APPLICANT(S) Lutz et al.	
	FILING DATE July 25, 2003	GROUP ART UNIT 2822

U.S. PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE
	4,849,071	7/1989	Evans et al.			
	4,945,769	8/1990	Sidner et al.			
	5,445,991	8/1995	Lee			
	5,470,797	11/1995	Mastrangelo			
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	5,338,416	8/1994	Mlcak et al.			
	6,808,954	10/2004	Ma et al.			
	2004-0065932	4/2004	Reichenbach et al.			

FOREIGN PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER	DATE CONSIDERED
EXAMINER: Initial citation if reference was considered. Draw line through citation if not in conformance to MPEP 609 and not considered. Include copy of this form with next communication to applicant.	

PTO-1449 (Modified) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO. 207.008-US	SERIAL NUMBER 10/627,237
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FOREIGN PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO	
	WO 01/46066	6/2001	PCT				
	GB 2 198 611	6/1988	Great Britain				
	WO 97/49475	12/1997	PCT				
	EP 0 451 992	10/1991	European				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	"Permeable Polysilicon Etch-Access Windows for Microshell Fabrication", Leboutz K S et al., International Conference on Solid-State Sensors and Actuators and Eurosensors, 25 June 1995 (1996-06-25), pp. 224-227
	"Porous Polycrystalline Silicon: A New Material for MEMS", Anderson R C et al., Journal of Microelectromechanical Systems, March 1994, USA, vol. 3, no. 1, pp.10-18
	"Vacuum Encapsulation of Resonant Devices Using Permeable Polysilicon", Leboutz et al., 1999 IEEE, pp.470-475
	"Laterally Grown Porous Polycrystalline Silicon: A New Material for Transducer Applications", Anderson et al., 1991 IEEE, pp.747-750

EXAMINER	DATE CONSIDERED
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